

ARMOR COMPETITION REPORT IEEE-TESCo

Introduction

As part of the celebration of the fifteenth anniversary of the TESCo July 6 2011, took place the second contest armor pasta, which was aimed at students in the second semester of Engineering Electromechanical and Mechatronic Engineering, in matters Mechanics Materials and Statics, as an additional project which helped them apply knowledge acquired during the course.

Bases

In the first stage of the competition, proposed the armor design considered by the teams, which according to its mathematical analysis had the best response to the application of a vertical load on its node bottom center, where a wooden tablet (loading platform) was placed with the following measures (0.5 cm x 5 cm x 2.5 cm).

Analysis of armor equipment, delivered two days before the day of event.

The materials for the construction of armor, were spaghetti number 7, joining only with epoxy resin.

The net length of the reinforcement was free, greater than 50 cm, width is 5 cm with a weight of less than 250 grams, otherwise was penalized with 10 grams more than the weight limit was rest 500 grams to the total load resisted by armor.



The test loads consisted of placing my water bottles with 500 grams each, until the structure is beat, counting aesthetic design in case of tie.

Judges

The winners were chosen by the judges M. in C. Sergio Foyo Antonio Valdez, Ivonne Mejia Caballero, who were invited by M. in C. Santillan Francisco Barbosa, director of Branch.

Awards

Two variables were considered to evaluate the resistance of the structure. The first according to their mathematical analysis (predicted load), and second one that would support greater load.

In the first three places were awarded recognition for their Participation in the competition. The names of the winning structures are following:

1. "The Chueca"
2. "Bruklin"
3. "Armageddon"

The event and awards ceremony was held in the auditorium of TESCo, where it was placed a stand of IEEE collateral, in order to invite participants and attendees to join the IEEE Student Branch-TESCo supporting us with advertising materials provided by IEEE, such as brochures, brochures, to provide information to the student community.



Thanks

We thank Dr. Francisco Plata Olvera, Director General of Technology Coacalco Higher Studies, the C. P. Jorge Hernández Hernández, Director of Administration and Finance TESCo, the M. C Angel Diaz Pineda, Mentor and Assistant Director of IMT - IEM - ISC TESCo, the M. in C. Francisco Barbosa Santillan, Counsellor-TESCo IEEE Student Branch, and to all members who participated in the organization without their collaboration would not have been possible to hold this event IEEE.



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Periodo Marzo 2011 - Marzo 2012

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